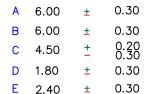
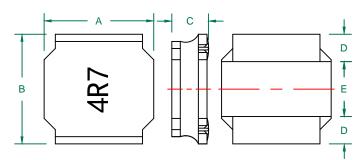
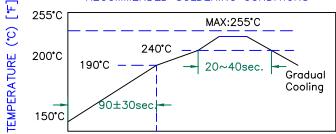
TYS60454R7M-10

PHYSICAL DIMENSIONS:

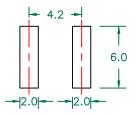


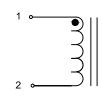


RECOMMENDED SOLDERING CONDITIONS



LAND PATTERNS FOR REFLOW SOLDERING

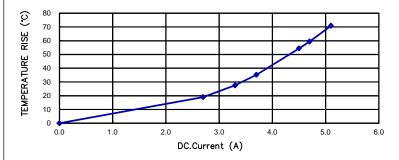




ELECTRICAL SPECIFICATION

	Min	Nom	Max
INDUCTANCE (uH) L @ 100KHz/1V ± 20%	3.76	4.70	5.64
DCR (Ω)		0.026	0.0338

CHARACTERISTICS OF TEMPERATURE RISE





Saturation Current(A)	4.97
SRF (MHz)	24
Temperature Rise Current (A)	3.30

CURRENT VS INDUCTANCE DROP IN RATES

10%					
-20%					
-30%					
50%					
50%					
60%					
70%					
80%					
90%					
00%	1				
	 2	3	4	5	

NOTES:

- 1.OPERATION TEMPERATURE RANGE: -40°C~+125°C (INCLUDING SELF-HEATING).
- 2.STORAGE TEMPERATURE RANGE (PACKAGING CONDITIONS): -10°C TO +40°C AND RH 70% (MAX.)
- 3.UNLESS OTHERWISE SPECIFIED, THE STANDARD ATMOSPHERIC CONDITIONS FOR MEASUREMENT/TEST AS:
 A. AMBIENT TEMPERATURE: 20±15°C.
 B. RELATIVE HUMIDITY: 65%±20%.
- 4.SATURATION CURRENT IS THE DC CURRENT AT WHICH THE INDUCTANCE DROPS OFF
 APPROXIMATELY 30% FROM ITS VALUE WITHOUT CURRENT.(AMBIENT TEMPERATURE 25±5°C)
- 5.TEMPERATURE RISE CURRENT (IRMS):

DC CURRENT THAT CAUSES THE TEMPERATURE RISE (△T ≤40°C) FROM 25°C AMBIENT.

	DIMENSIONS ARE IN mm .		1	This print is the property of Laird Tech, and is loaned in confidence						
				subject to return upon request of with the understanding that no		Ì	2	irc	-	
				copies shall be made without the written consent of Laird Tech. A		_	_a	T# /		
				rights to design or invention are reserved.						
		<u> </u>		PROJECT/PART NUMBER:	R	EV	PART TO	PE:	DRAWN BY:	
С	CHANGE DIMENSIONS C/D/E	08/18/16		TYS60454R7M-10		С		WER CTOR	QIU	
В	CHANGE TEMP FROM&ADD CURVE	01/02/13	QIU	_ CAD # 10		5 NI	TC	SHEET:		
Α	ORIGINAL DRAFT	12/07/12	QIU			NTS SHEET			of 1	
REV	DESCRIPTION	DATE	INT					1		